LOCTITE®

Chipbonder® Surface Mount Adhesive

Technology that Sticks

Henkel

From pioneering beginnings as the first commercially available adhesive for the Surface Mount Technology market, Loctite® Chipbonder® is today's adhesive of choice for assembly specialists worldwide. For mixed-technology and double-sided SMT applications, Chipbonder® is the name to trust.

KRAYDEN, INC.

AUTHORIZED DISTRIBUTOR

1-800-448-0406

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Loctite® Chipbonder® products are particularly well-suited for applications where very high speed dispensing, high dot profiles, superior wet strength and high electrical specifications are required. Like all Henkel products, Loctite® Chipbonder® Adhesives are available in a variety of formulations to meet customer-specific requirements.

Low-Temperature and Screen Printable

Loctite® 3629™ Chipbonder® Adhesive delivers a low-temperature cure with very fast and highly reliable characteristics. This innovative material provides energy savings from reduced temperature curing and is compatible with modern lead-free processes. With robust properties, Loctite® 3629™ Chipbonder® Adhesive has been optimized for high-speed printing processes and is qualified for use with DEK® ProFlow® printing and the MPM® Rheopump.

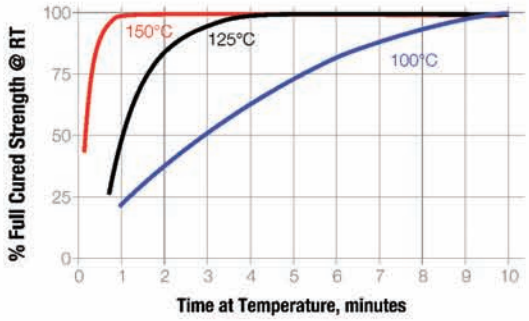
Dispensing

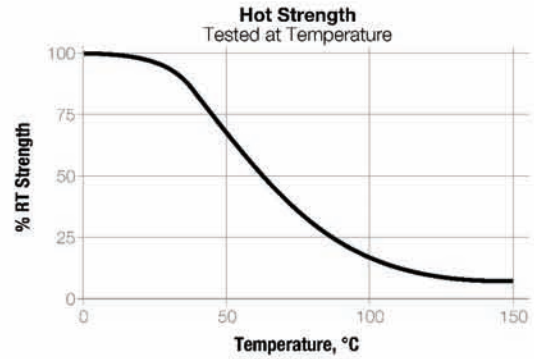
Loctite® 3609™, Loctite® 3627™ and Loctite® 3629™ Chipbonder® Adhesives have all been formulated to address unique manufacturing requirements, including lead-free processing, high-speed dispensing and high-humidity applications. Material viscosity has also been optimized for superior dispense performance.

Ultra High-Speed Dispensing

Recognizing that some operations require dispense speeds beyond the mainstream, Henkel has developed Loctite® 3621™ Chipbonder® Adhesive for applications that require ultra fast capability. For speeds greater than 35,000 dots per hour, lead-free capable Loctite® 3621™ Chipbonder® Adhesive is the premiere material.

PRODUCT CHARACTERISTICS	
Technology	Epoxy
Chemical Type	Epoxy
Appearance (uncured)	Dark red viscous gel LMS
Components	One component – requires no mixing
Cure	Heat Cure
Application	Surface Mount Adhesive
Key Substrates	Electronic components to printed circuit boards
Other Application Areas	Small Parts Bonding
Dispense Method	Syringe
Dispense Speed	Medium 15,000-25,000 dph
Wet Strength	High
Dot Profile	Peaked
Operating Temperature	-54°C to +150°C





CHEMICAL/SOLVENT RESISTANCE				
		% of initial strength		
Environment	**°C**	**100 hr.**	**500 hr.**	**1000 hr.**
Air	22	100	100	95
Air	150	85	70	70
Heat/Humidity 98% RH	40	110	110	100
Freon® 113	22	100	100	100
Terpene	22	100	100	100

Aged under conditions indicated and tested at 22°C.

Across the Board, Around the Globe.

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